Product End-of-Life Disassembly Instructions

Product Category: Calculators
Marketing Name / Model [List multiple models if applicable.]
HP MSR3012 AC Router (JG409A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

PSG instructions for this template are available at EL-MF877-01

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew all screws 1, and then remove the mounting angle 2.
2. Unscrew the screws on filler panel 3, and then remove filler panel 3.
3. Unscrew the screws on card 4, and then remove card 4.
4. Unscrew the screws on filler panel 5, and then remove filler panel 5.
5. Unscrew the screws on card 6, and then remove card 6.
6. Unscrew the screws on cover 7, and then remove cover 7.
7. Unscrew the screws on part 8, and then remove part 8.
8. Unscrew the screws on part 9, and then remove part 9.
9. Remove film 10 from film 18.
10. Unscrew the screws on panel 11, and then remove panel 11.
11. Unscrew the Power Cable Holder 12
12. Unscrew the screws on power bracket 13, and then remove power bracket 13.
13. Unscrew the screws on PCB 15, and then remove PCB 15.
14. Unscrew the screws on PCB 14, and then remove PCB 14.
15. Unscrew all screws on fan 16, and then remove fan 16 from the chassis.
16. Remove film 18 from plastic panel 17.
17. Unscrew the screws on plastic panel 17, and then remove plastic panel 17.
18. Remove screws 19 from the chassis.
19. Remove part 20 from the chassis.
20. Unscrew all screws on fan 9-2, and then remove fan 9-2 from the bracket 9-1.
21. Unscrew the screws on power 13-3, and then remove power.
22. Remove plastic panel 13-2 from bracket 13-1.
23. Unscrew the screws on PCB 15-2, and then remove PCB 15-2.
24. Remove part 14-2 from the PCB 14-1.
25. Remove part 14-5 from the PCB 14-1.
26. Remove part14-3 from the PCB 14-4

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

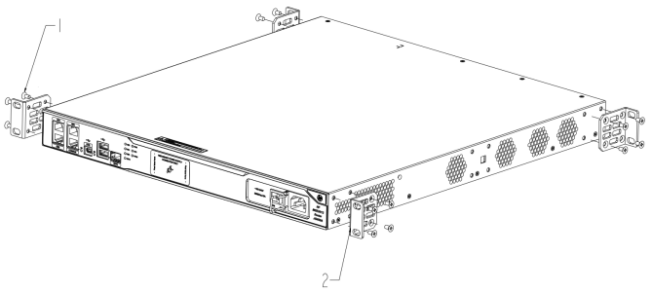

Figure 1 Treatments to the product

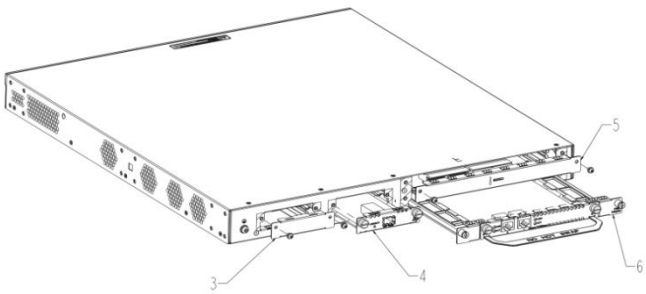

Figure 2 Treatments to the product

PSG instructions for this template are available at EL-MF877-01

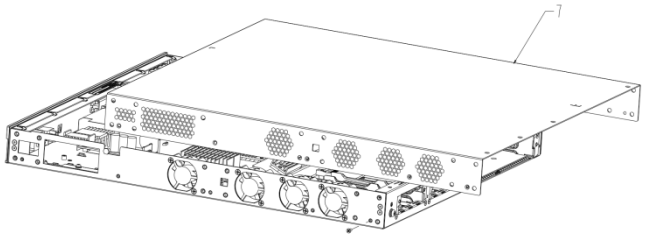

Figure 3 Treatments to the product

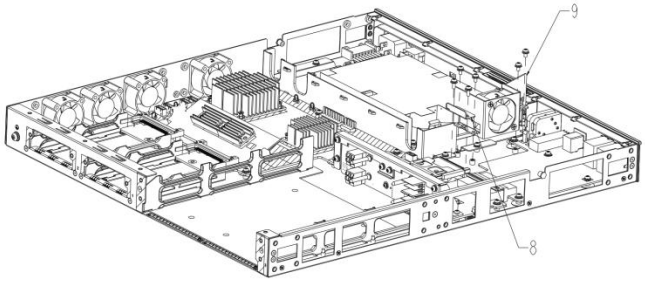

Figure 4 Treatments to the product

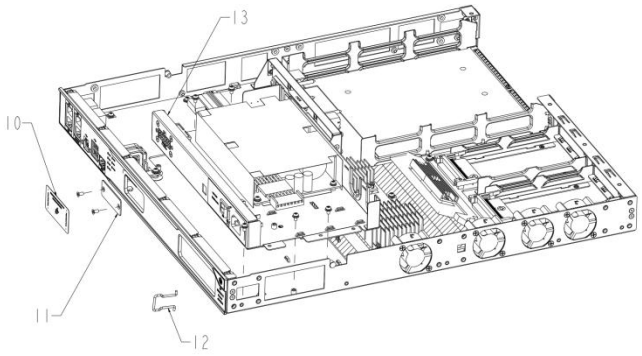

Figure 5 Treatments to the product

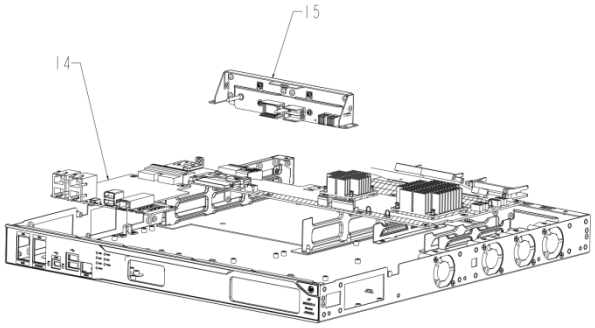

Figure 6 Treatments to the product

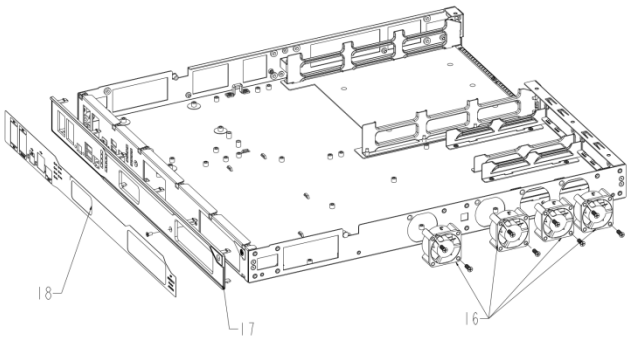

Figure 7 Treatments to the product

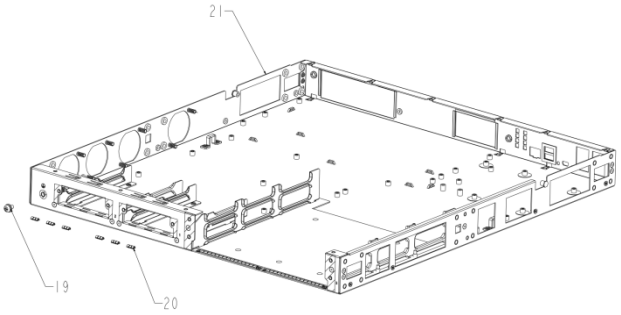

Figure 8 Treatments to the product

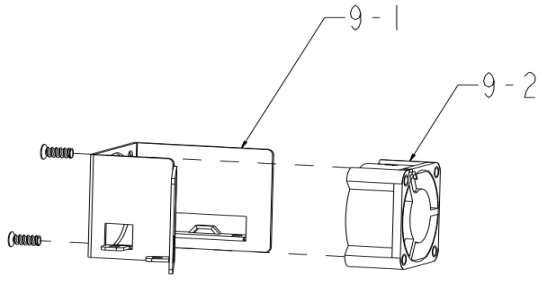

Figure 9 Treatments to the product

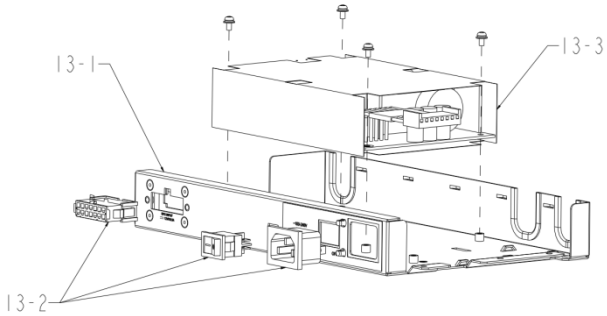

Figure 10 Treatments to the product

PSG instructions for this template are available at EL-MF877-01

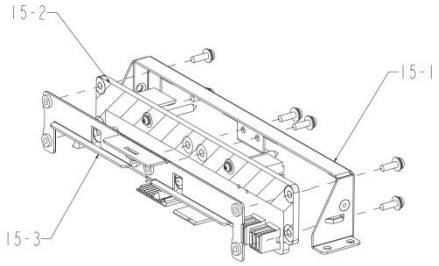

Figure 11 Treatments to the product

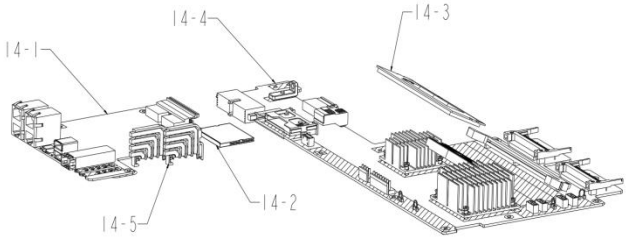

Figure 12 Treatments to the product

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
	2	Fe	38.4	0.6%		Fe recycling
	3	Fe	17.6	0.3%		Fe recycling
	5	Fe	26.8	0.4%		Fe recycling
	7	Fe	2033.9	31.5%		Fe recycling
9						
	9-1	Fe	52.5	0.7%		Fe recycling
	9-2	PBT , Cu	33	0.48%	Containing brominated flame retardants	Pla recycling Cu recycling
13						
	13-1	Fe	486.2	7.2%		Fe recycling
	13-3	PBT , Cu	450	6.7%	Containing brominated flame retardants	Pla recycling Cu recycling
14						
	14-1	Complex PWB	150	2.2%	The surface of PCB is greater than 10 square centimeters;	
	14-4	Complex PWB	450.5	6.7%	The surface of PCB is greater than 10 square centimeters;	
15						
	15-1	Fe	68.9	1%		Fe recycling
	15-2	Complex PWB	70.6	1.4%	The surface of PCB is greater than 10 square centimeters;	
	16	PBT , Cu	33*4	1.9%	Containing brominated flame retardants	Pla recycling Cu recycling
	17	PBT	40.6	0.6%	Containing brominated flame retardants	Pla recycling
	21	Fe	2492.6	37.4%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2012.12.11	V0	Liu Jia	Initial version